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(54) SEMICONDUCTOR ELEMENT WITH MULTILAYERED PAD, AND MANUFACTURE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor
element provided with a multilayered pad, with which the
generation of cracks can be minimized by optimizing the
structure of a bonding pad, and to provide a manufacturing
method of the semiconductor element.

SOLUTION: A first conductive pad 124, which extends
long along one open face of the case part of a pad window
region 140, is formed on the semiconductor substrate 120
provided with a first interlayer insulating film 122. A
second interlayer insulating film 128, having a first via hole
126 used to expose the surface of the first conductive
pad 124, is formed on the first interlayer insulating film
122, and a first conductive plug 127 is formed in the first
via hole 126. A second conductive pad 130, to be
connected to the first conductive plug 127, is formed on
the second interlayer insulating film 128. A third interlayer
insulating film 134, provided with a second via hole 132
used to expose the surface of the second conductive pad
is formed, and a second conductive plug 133 is formed in
the via hole 132. A third conductive pad 136 is formed on the third interlayer insulating film 134,
in such a manner that it is connected to the second conductive plug 133.
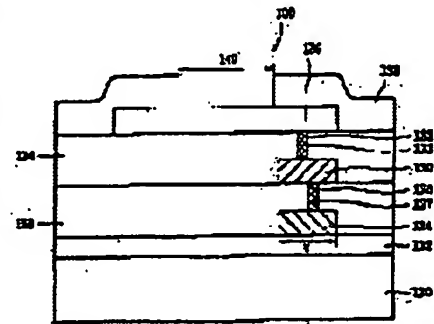
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